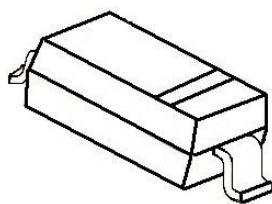


SOD-123**Marking: SM****SOD-123 Plastic-Encapsulate Schottky Barrier Diode****特征 Features**

- 大电流承受能力.High Current Capability
- 正向压降低.Low Forward Voltage Drop
- 漏电流小.Low IR

机械数据 Mechanical Data

- 封装: SOD-123 封装 SOD-123 Small Outline Plastic Package
- 极性: 色环端为负极Polarity: Color band denotes cathode end
- 环氧树脂UL 易燃等级Epoxy UL: 94V-0
- 安装位置: 任意 Mounting Position: Any

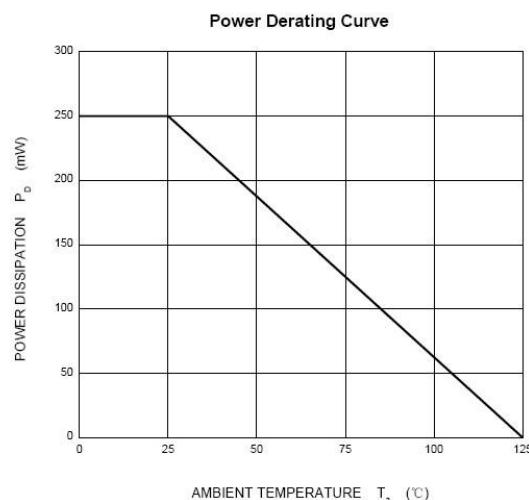
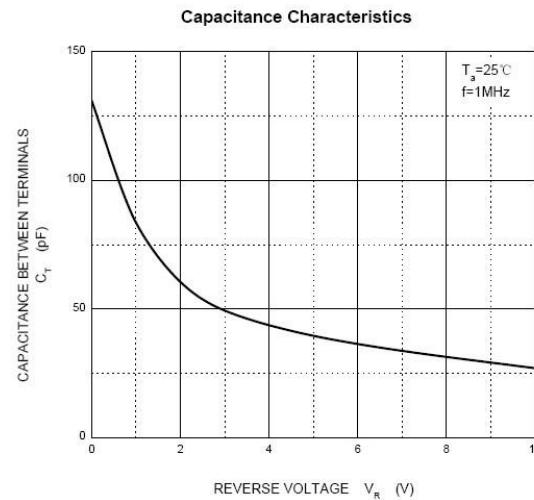
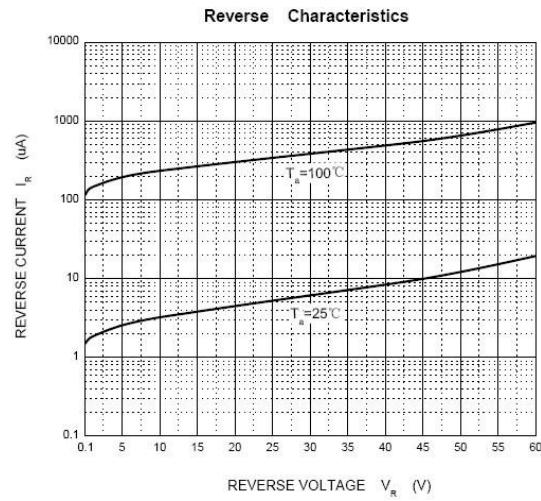
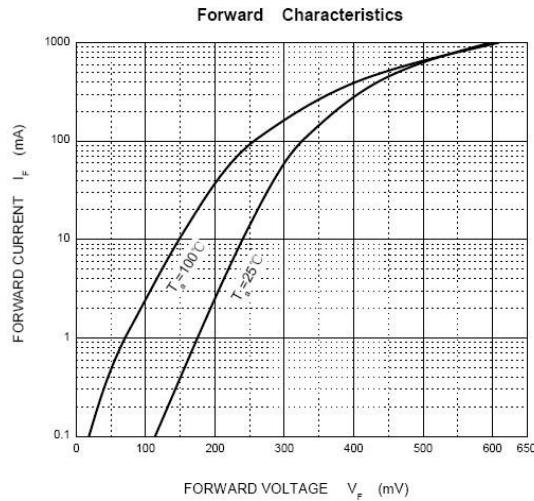
极限值和温度特性($TA = 25^\circ\text{C}$ 除非另有规定)**Maximum Ratings & Thermal Characteristics** (Ratings at 25°C ambient temperature unless otherwise specified.)

参数 Parameters	符号 Symbol	数值 Value	单位 Unit
最大可重复峰值反向电压 Maximum repetitive peak reverse voltage	V _{RRM}	60	V
最大均方根电压 Maximum RMS voltage	V _{RMS}	42	V
最大直流阻断电压 Maximum DC blocking voltage	V _{DC}	60	V
最大正向平均整流电流 Maximum average forward rectified current	I _{FM}	1	A
峰值正向浪涌电流 8.3ms 单一正弦半波 Peak forward surge current 8.3 ms single half sine-wave	I _{FSM}	10	A
典型热阻 Typical thermal resistance	R _{θJA}	400	°C/W
功率消耗 Power Dissipation	P _D	250	mW
结温 Junction temperature	T _J	125	°C
存储温度 Storage temperature range	T _{STG}	-55~+150	°C

电特性 ($TA = 25^\circ\text{C}$ 除非另有规定)**Electrical Characteristics** (Ratings at 25°C ambient temperature unless otherwise specified.)

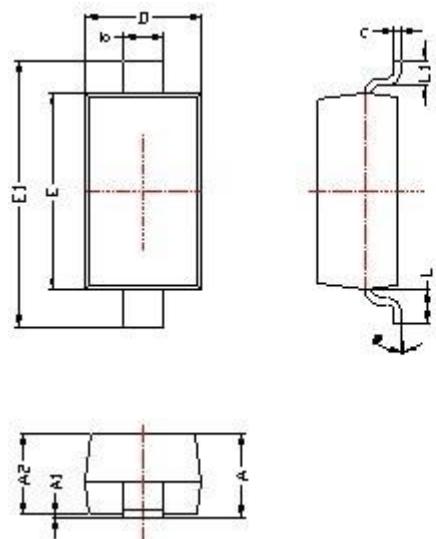
参数 Parameters	符号 Symbol	测试条件 Test conditions	数值 Value	单位 Unit
最大正向电压 Maximum forward voltage	V _F	I _F = 1.0A	0.70(max.)	V
最大反向电流 Maximum reverse current	I _R	V _R =60V	100(max.)	uA

特性曲线Characteristic Curves



SOD-123 PACKAGE OUTLINE

Plastic surface mounted package

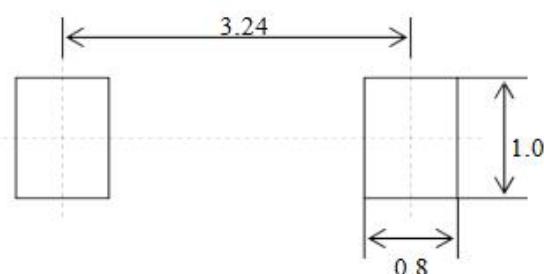


SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	1.050	1.250
A1	0.000	0.100
A2	1.050	1.150
b	0.450	0.650
c	0.080	0.150
D	1.500	1.700
E	2.600	2.800
E1	3.550	3.850
L	0.500REF	
L1	0.250	0.450
θ	0°	8°

焊盘设计参考

Precautions: PCB Design

Recommended land dimensions for SOD-123 diode. Electrode patterns for PCBs



技术要求:

- 中心距: 3.24 1. 塑封体尺寸: 2.70 X 1.60
 脚 宽 : 0.55 2: 未注公差为: ±0.05
 焊盘宽: 1.00 3. 所有单位: mm
 脚 长 : 0.50
 焊盘长: 0.80